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Margaret S. FyfieldFILING DATE
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U.S. PATENT DOCUMENTS

EXAM. INIT.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB- CLASS	FILING DATE IF APPRO- PRIATE

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB- CLASS	TRANSLA- TION		
					YES	NO	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

Gary Shade and Kendall Scott Wills, *Photoemission Microscopy*, 1997 ASM International, pp. 181-182B. Bossman, P. Baurachmild, K. Hussey, and E. Black, *Failure Analysis Techniques with the Confocal Laser Scanning Microscope*, ISTFA '92: The 18th International Symposium for Testing & Failure Analysis, October 1992, pp. 351-361Nevil M. Wu, Kevin Weaver, James H. Lin, *Failure Analysis from Back Side of Die*, ISTFA '96: 22nd International Symposium for Testing and Failure Analysis, November 1996, 7 pagesT.W. Joseph, A.L. Berry, B. Bossman, *Infrared Laser Microscopy of Structures on Heavily Doped Silicon*, ISTFA '92: The 18th International Symposium for Testing & Failure Analysis, October 1992, pp. 1-7D.L. Barton, P. Tangyunyong, J.M. Soden, A.Y. Liang, F.J. Low, A.N. Zaplatin, K. Shivanandan, and G. Donohoe, *Infrared Light Emission from Semiconductor Devices*, Proceedings of the 22nd International Symposium for Testing and Failure Analysis, November 1996, pp. 9-17Chun-Cheng Tsao, Steven, Kasapi, and Kurt Hurley, *Backside waveform probing of CMOS devices using infrared laser at wavelength of 1064 nm*, 6 pagesC. Chiang, N. Khurana, D.T. Hurley, and K. Teasdale, *Backside Emission Microscopy for Integrated Circuits on Heavily Doped Substrate*, Proceedings from the 24th International Symposium for Testing and Failure Analysis, November 1998, pp. 447-453Kendall Scott Wills, Terri Lewis, Greg Baus, Hai Hoang, *Optical Beam Induced Current Applications for Failure Analysis of VLSI Devices*, 1997 ASM International, pp. 21-26Yoch Eng Hong and Martin Tay Tiong We, *The application of novel Failure Analysis Techniques for Advanced Multi-Layered CMOS devices*, 6 pagesT. Koyama, Y. Mashiko, M. Sekine, H. Koyama and K. Horie, *New non-bias optical beam induced current (NB-OBIC) techniques for evaluation of Al interconnects*, 1995 IEEE, pp. 228-233Said F. Al-sarawi, *Tape-Automated Bonding*, Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March 1997, pp. 1-2Said F. Al-sarawi, *Solder Bump Bonding*, Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March 1997, 1 page

EXAMINER

DATE CONSIDERED

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